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# FQB22P10

## P-Channel QFET® MOSFET

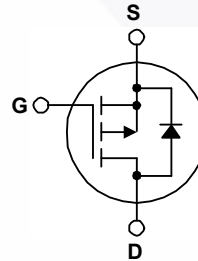
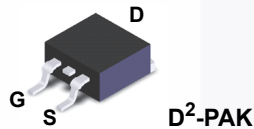
-100 V, -22 A, 125 mΩ

### Description

This P-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

### Features

- -22 A, -100 V,  $R_{DS(on)} = 125 \text{ m}\Omega$  (Max) @  $V_{GS} = -10 \text{ V}$ ,  $I_D = -11 \text{ A}$
- Low Gate Charge (Typ. 40 nC)
- Low Crss (Typ. 160 pF)
- 100% Avalanche Tested
- 175°C Maximum Junction Temperature Rating



### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FQB22P10TM	Unit
$V_{DSS}$	Drain-Source Voltage	-100	V
$I_D$	Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ )	-22	A
	- Continuous ( $T_C = 100^\circ\text{C}$ )	-15.6	A
$I_{DM}$	Drain Current - Pulsed (Note 1)	-88	A
$V_{GSS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	710	mJ
$I_{AR}$	Avalanche Current (Note 1)	-22	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	12.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	-6.0	V/ns
$P_D$	Power Dissipation ( $T_A = 25^\circ\text{C}$ ) *	3.75	W
	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	125	W
	- Derate above $25^\circ\text{C}$	0.83	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +175	$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	FQB22P10TM	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	1.2	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (minimum pad of 2 oz copper), Max.	62.5	
	Thermal Resistance, Junction to Ambient (* 1 in <sup>2</sup> pad of 2 oz copper), Max.	40	

## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FQB22P10	FQB22P10TM	D2-PAK	330mm	24mm	800

## Electrical Characteristics

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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### Off Characteristics

$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$	-100	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = -250\ \mu\text{A}$ , Referenced to $25^\circ\text{C}$	--	-0.1	--	V/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = -100\text{ V}, V_{GS} = 0\text{ V}$	--	--	-1	$\mu\text{A}$
		$V_{DS} = -80\text{ V}, T_C = 125^\circ\text{C}$	--	--	-10	$\mu\text{A}$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA

### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	-2.0	--	-4.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = -10\text{ V}, I_D = -11\text{ A}$	--	0.096	0.125	$\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = -40\text{ V}, I_D = -11\text{ A}$	--	13.5	--	S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = -25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	1170	1500	pF
$C_{oss}$	Output Capacitance		--	460	600	pF
$C_{rss}$	Reverse Transfer Capacitance		--	160	200	pF

### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = -50\text{ V}, I_D = -22\text{ A},$ $R_G = 25\ \Omega$	--	17	45	ns
$t_r$	Turn-On Rise Time		--	170	350	ns
$t_{d(off)}$	Turn-Off Delay Time		--	60	130	ns
$t_f$	Turn-Off Fall Time		(Note 4)	--	110	230
$Q_g$	Total Gate Charge	$V_{DS} = -80\text{ V}, I_D = -22\text{ A},$ $V_{GS} = -10\text{ V}$	--	40	50	nC
$Q_{gs}$	Gate-Source Charge		--	7.0	--	nC
$Q_{gd}$	Gate-Drain Charge		(Note 4)	--	21	--

### Drain-Source Diode Characteristics and Maximum Ratings

$I_S$	Maximum Continuous Drain-Source Diode Forward Current	--	--	-22	A	
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current	--	--	-88	A	
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = -22\text{ A}$	--	--	-4.0	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_S = -22\text{ A},$ $dI_F / dt = 100\text{ A}/\mu\text{s}$	--	110	--	ns
$Q_{rr}$	Reverse Recovery Charge		--	0.6	--	$\mu\text{C}$

#### Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2.  $L = 2.2\text{mH}, I_{AS} = -22\text{A}, V_{DD} = -25\text{V}, R_G = 25\ \Omega$ , Starting  $T_J = 25^\circ\text{C}$
3.  $I_{SD} \leq -22\text{A}, di/dt \leq 300\text{A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$
4. Essentially independent of operating temperature

## Typical Characteristics

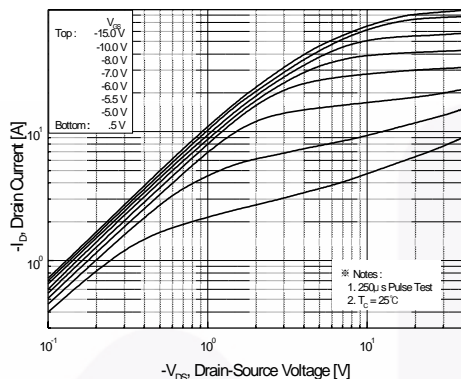


Figure 1. On-Region Characteristics

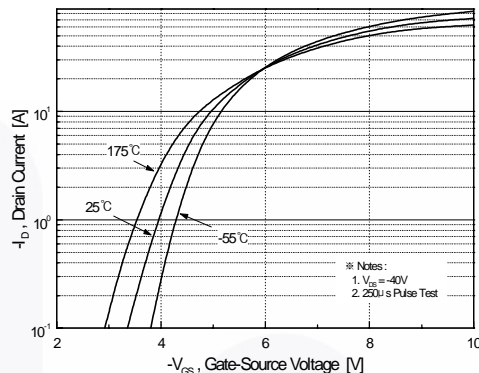


Figure 2. Transfer Characteristics

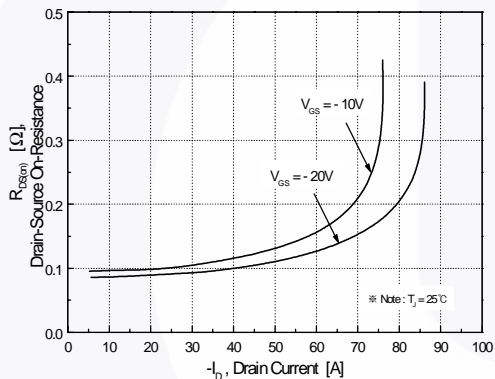


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

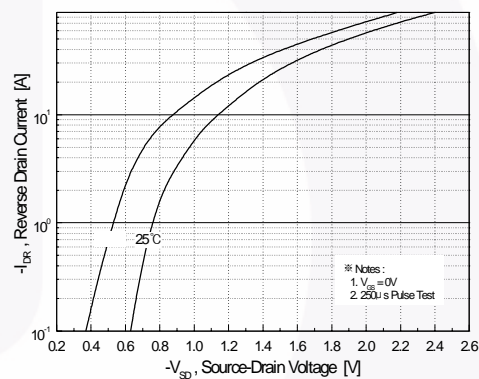


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

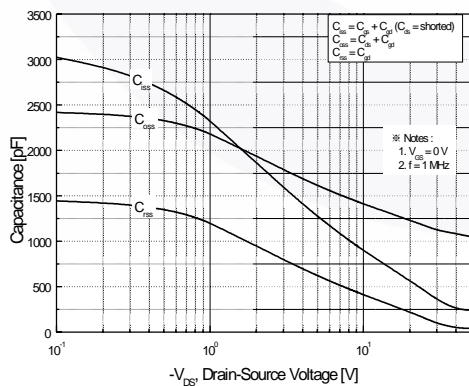


Figure 5. Capacitance Characteristics

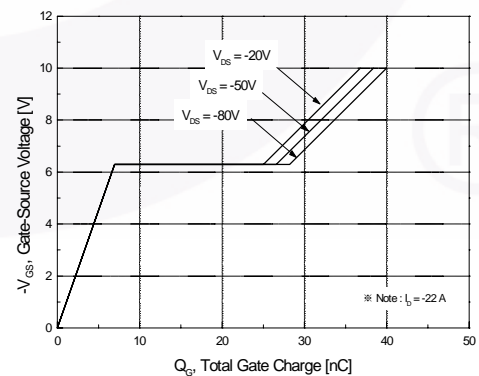
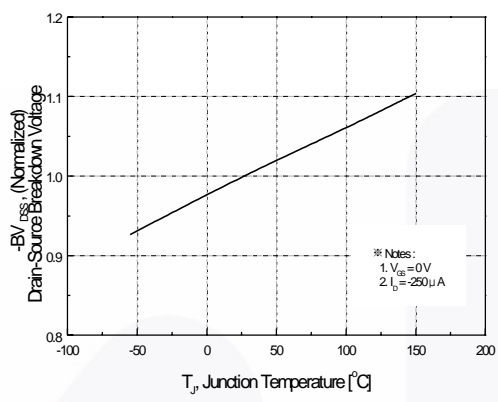
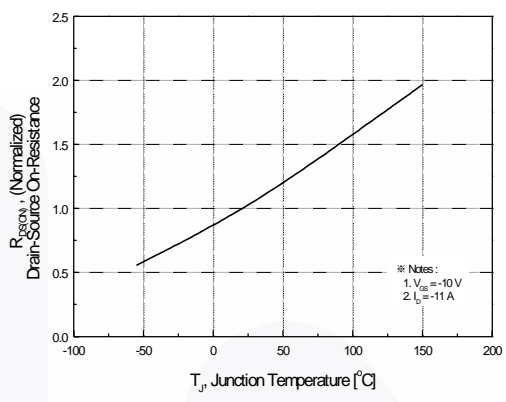


Figure 6. Gate Charge Characteristics

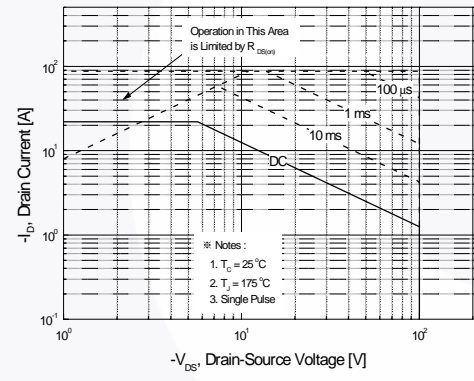
**Typical Characteristics** (Continued)



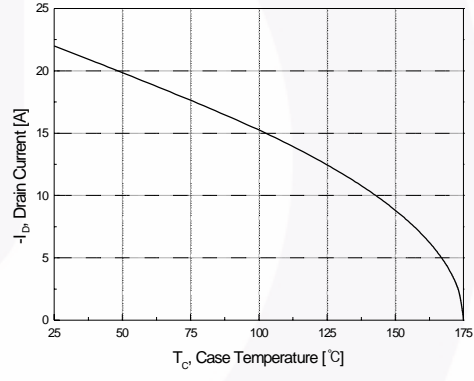
**Figure 7. Breakdown Voltage Variation vs. Temperature**



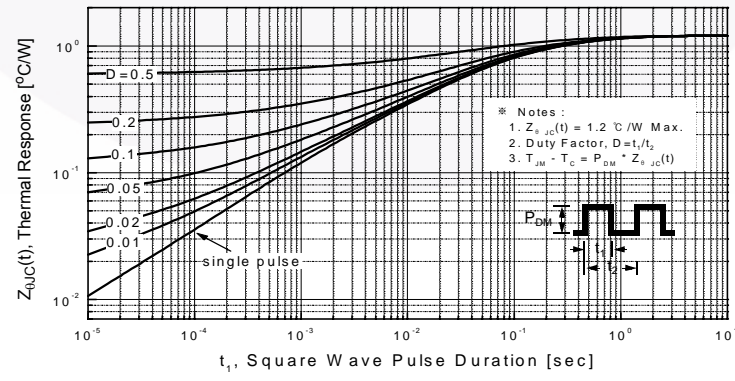
**Figure 8. On-Resistance Variation vs. Temperature**



**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current vs. Case Temperature**



**Figure 11. Transient Thermal Response Curve**

Figure 12. Gate Charge Test Circuit & Waveform

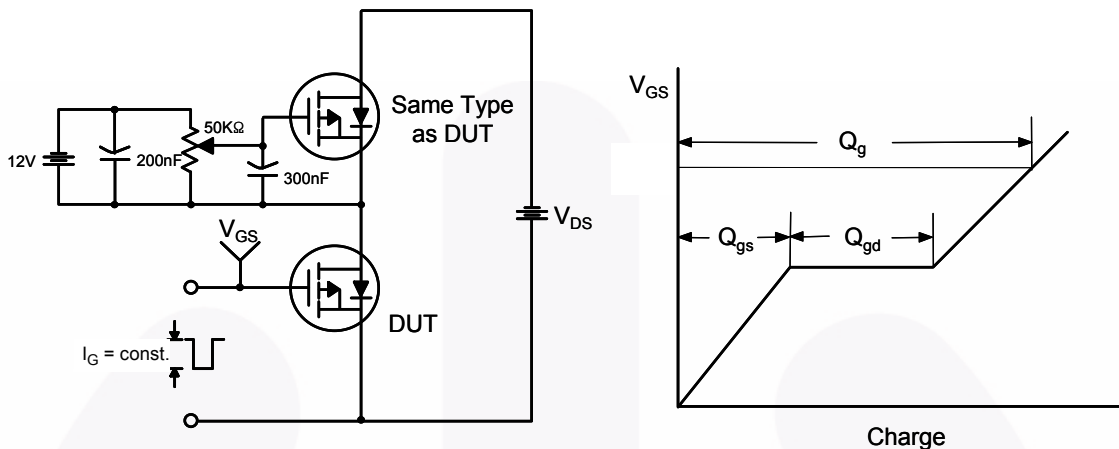


Figure 13. Resistive Switching Test Circuit & Waveforms

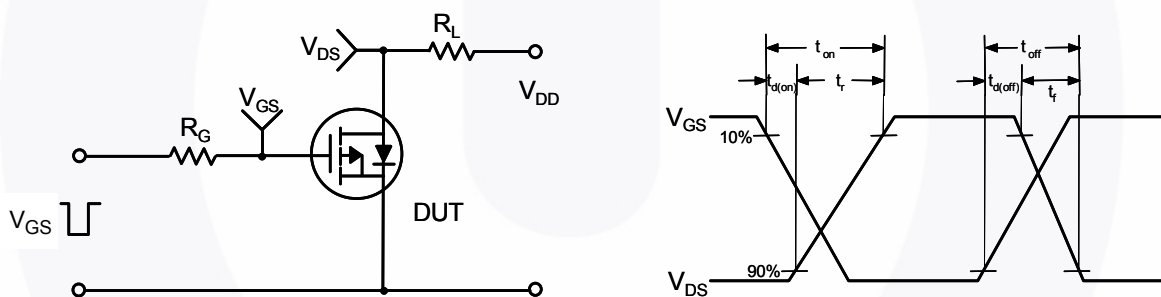


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

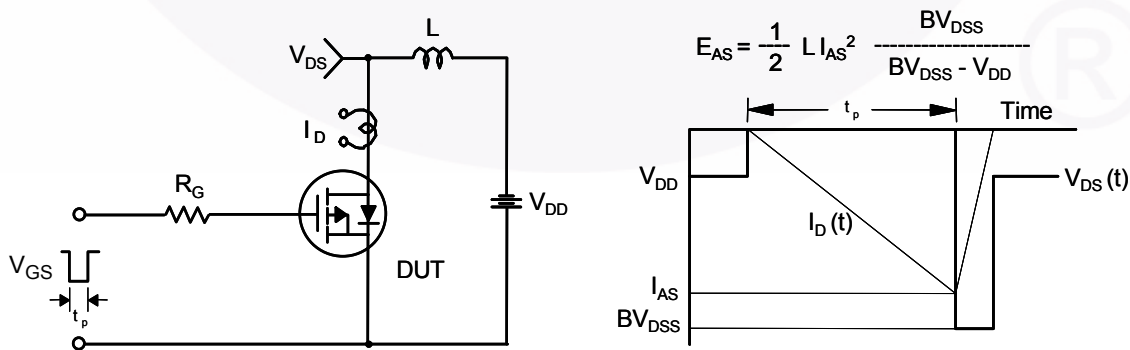
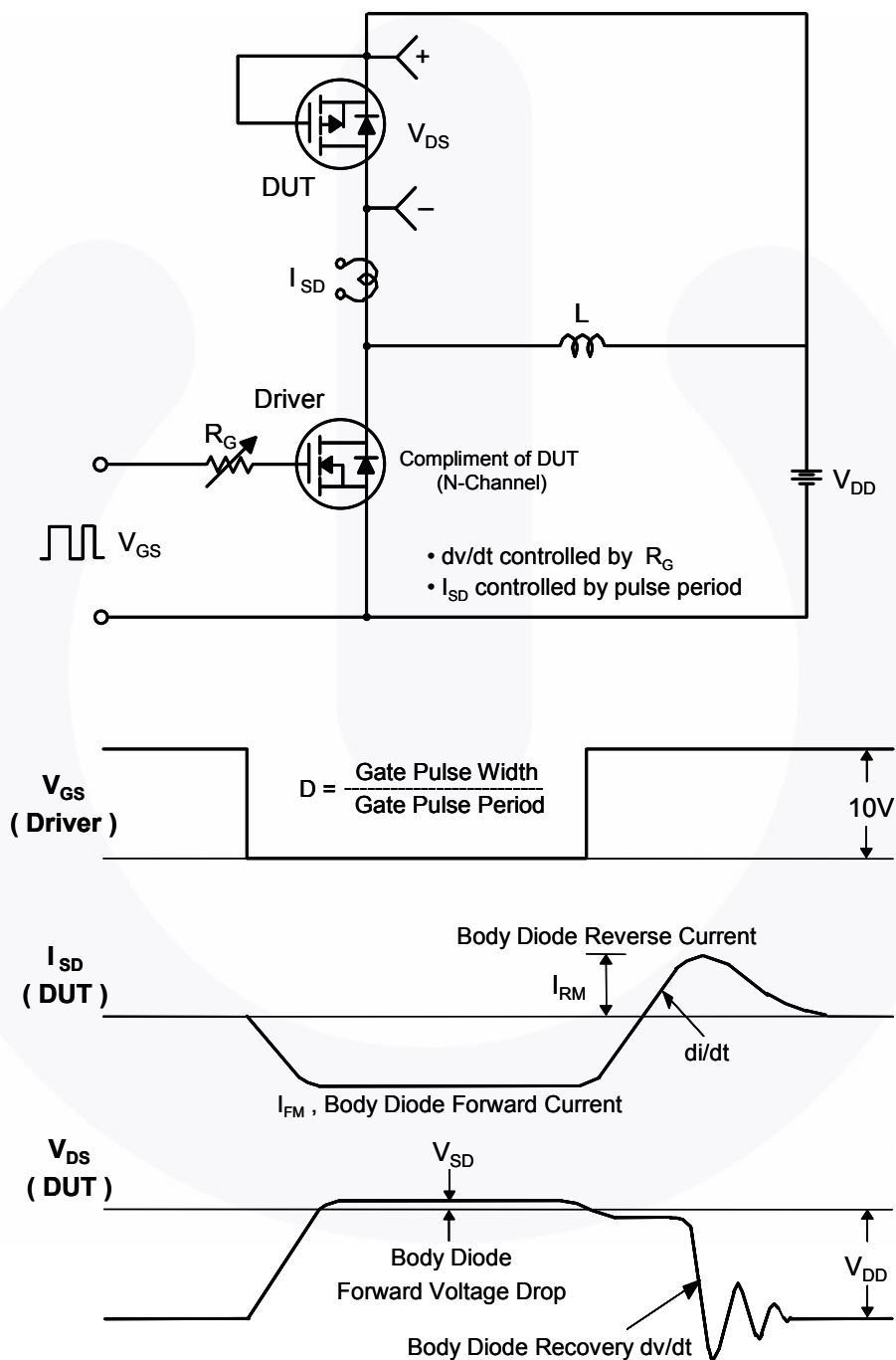
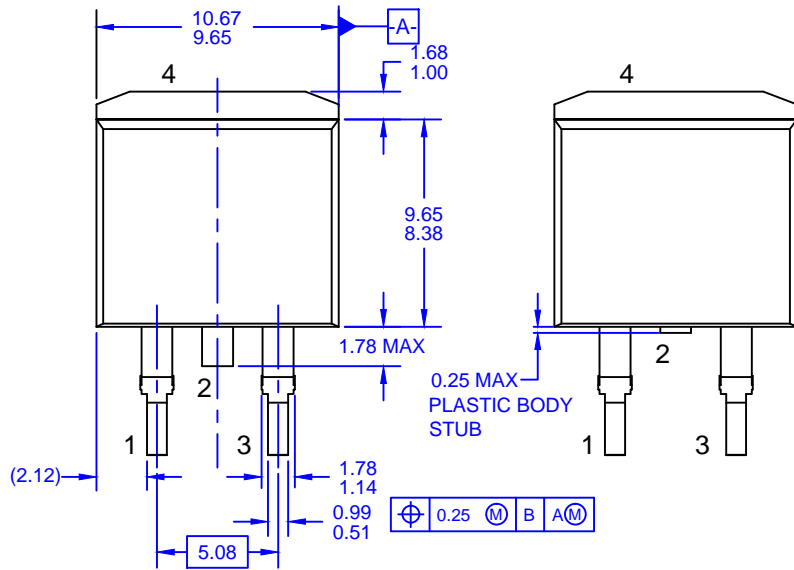
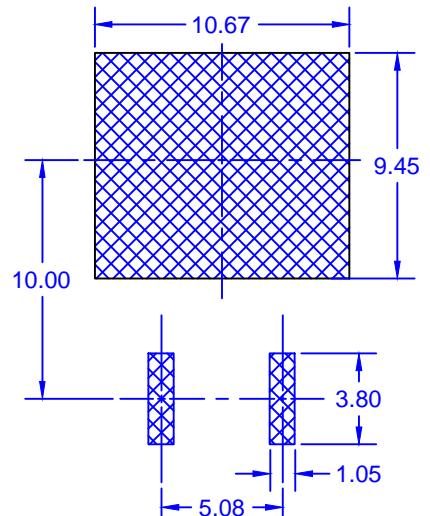


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

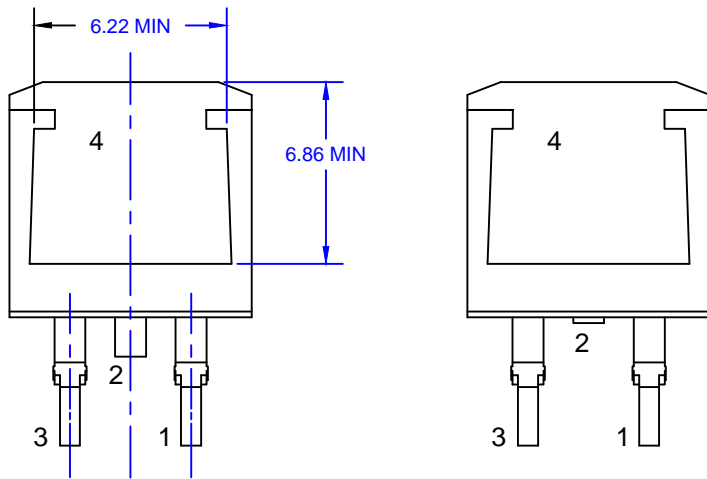




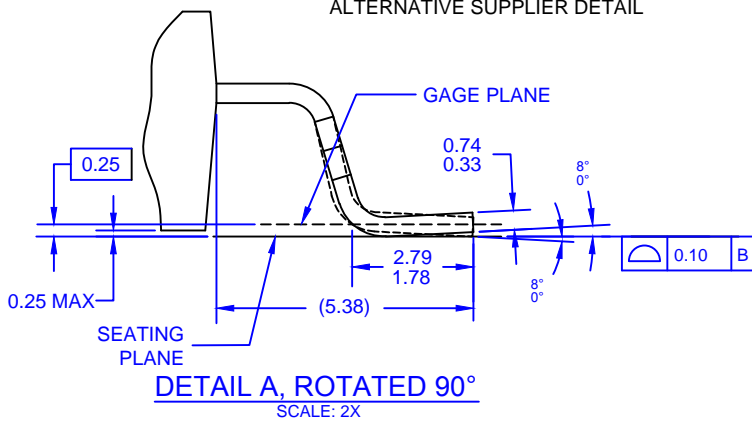
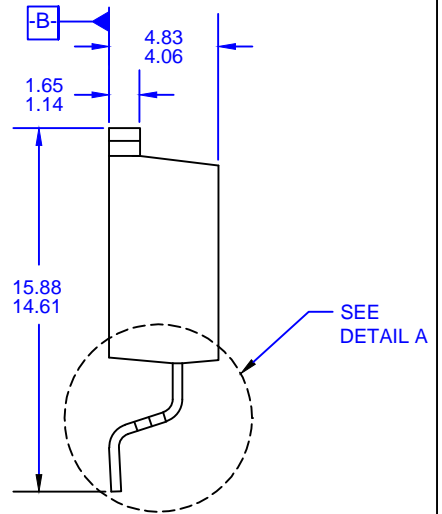
FRONT VIEW - DIODE PRODUCTS VERSION  
ALTERNATIVE SUPPLIER DETAIL



LAND PATTERN RECOMMENDATION  
UNLESS NOTED, ALL DIMS TYPICAL



BACK VIEW - DIODE PRODUCTS VERSION  
ALTERNATIVE SUPPLIER DETAIL



DETAIL A, ROTATED 90°  
SCALE: 2X

NOTES: UNLESS OTHERWISE SPECIFIED

- A) ALL DIMENSIONS ARE IN MILLIMETERS.
- B) REFERENCE JEDEC, TO-263, VARIATION AB.
- C) DIMENSIONING AND TOLERANCING PER ASME Y14.5 - 2009.
- D) LOCATION OF THE PIN HOLE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE).
- E) LANDPATTERN RECOMMENDATION PER IPC TO254P1524X482-3N
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